
**UNITED STATES
SECURITIES AND EXCHANGE COMMISSION**
Washington, D.C. 20549

FORM 8-K

CURRENT REPORT
Pursuant to Section 13 or 15(d)
of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): September 27, 2016

TTM TECHNOLOGIES, INC.

(Exact name of registrant as specified in its charter)

Delaware
(State or other Jurisdiction
of Incorporation)

0-31285
(Commission
File Number)

91-1033443
(IRS Employer
Identification No.)

1665 Scenic Avenue, Suite 250
Costa Mesa, California
(Address of Principal Executive Offices)

92626
(Zip Code)

Registrant's telephone number, including area code: (714) 327-3000

(Former name or former address if changed since last report.)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

- ☐ Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
 - ☐ Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
 - ☐ Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
 - ☐ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))
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Item 1.01. Entry into a Material Definitive Agreement.***Amendment to Credit Facilities***

On September 27, 2016, the Registrant entered into a First Amendment to amend and restate the Term Loan Credit Agreement (the “TLB Agreement”) dated May 31, 2015 among the Registrant, the several lenders from time to time parties thereto, JPMorgan Chase Bank, N.A., as administrative agent, and the other agents thereto. The TLB Agreement was amended to (a) reduce the amount outstanding under the TLB Agreement to \$775 million (which reflects the prepayment by the Registrant of approximately \$66 million in connection with the First Amendment), (b) reduce the applicable margin for Eurodollar Loans to 4.25% and the applicable margin for ABR Loans to 3.25% (which is a reduction of 0.75% for each type of loan), (c) institute a 1% prepayment premium for any prepayments made under the TLB Agreement in the next 12 months, (d) permit the Registrant to sell up to \$30 million of accounts receivable, and (e) make certain other changes to the TLB Agreement.

Also on September 27, 2016, the Registrant entered into a First Amendment to amend and restate the ABL Credit Agreement (the “ABL Agreement”) dated May 31, 2015 among the Registrant, the several lenders from time to time parties thereto, JPMorgan Chase Bank, N.A., as administrative agent, and the other agents thereto. The ABL Agreement was amended to (a) increase the amount available under the ABL Agreement to \$200 million (which increase was pursuant to the Registrant’s right to increase the availability pursuant to the original ABL Agreement), (b) reduce the applicable margins by 0.25% for both Eurodollar Loans and ABR Loans, (c) permit the Registrant to sell up to \$30 million of accounts receivable, and (d) make certain other changes to the ABL Agreement.

The foregoing summary of the amendments to the TLB Agreement and the ABL Agreement does not purport to be complete and is subject to, and qualified in its entirety by, the full texts of the amended and restated TLB Agreement and the amended and restated ABL Agreement.

Item 2.03. Creation of a Direct Financial Obligation or an Obligation under an Off-Balance Sheet Arrangement of a Registrant.

The disclosure required by this Item is included in Item 1.01 and is incorporated herein by reference.

Item 7.01. Regulation FD.

On September 27, 2016, the Registrant issued a press release announcing the amendment of the TLB Agreement and the ABL Agreement. A copy of the press release is attached as Exhibit 99.1 hereto and is incorporated by reference herein.

Item 9.01. Financial Statements and Exhibits.

(d) *Exhibits.*

<u>Exhibit No.</u>	<u>Description</u>
99.1	Press Release, dated September 27, 2016

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the Registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

Date: September 27, 2016

TTM TECHNOLOGIES, INC.

By: /s/ Daniel J. Weber

Daniel J. Weber
Senior Vice President,
General Counsel and Secretary

EXHIBIT INDEX

<u>Exhibit No.</u>	<u>Description</u>
99.1	Press Release, dated September 27, 2016



Contact:

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Investor Relations
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FOR IMMEDIATE RELEASE

TTM TECHNOLOGIES, INC. ANNOUNCES SUCCESSFUL REPRICING OF TERM B LOANS AND ASSET BASED LOAN

COSTA MESA, CA - September 27, 2016 - TTM Technologies, Inc. (NASDAQ: TTMI) ("TTM" or the "Company") today announced that it has successfully priced \$775 million of new U.S. dollar-denominated Term B Loans at an interest rate of LIBOR + 4.25%, which priced 75 basis points lower than its previous Term B Loans issued in May 2015. In connection with this transaction, TTM settled \$841 million of the previously outstanding U.S. dollar-denominated Term B Loans, thereby paying down approximately \$66 million of its previously outstanding Term B Loans. The new financing is expected to generate annual interest savings of approximately \$19.5 million. This consists of reduced cash interest payments of \$10.0 million and reduced non-cash interest expense of \$9.5 million. The new Term B Loans have the same remaining tenor as the previous Term B Loans and mature on May 31, 2021. In conjunction with this transaction, TTM will record, in the fourth quarter, non-cash expense of \$47.8 million for the write off of the original issuance discount of \$25.4 million and debt issuance costs of \$22.4 million associated with the Term B Loans originally issued in May 2015.

In addition, the Company has increased the availability of its revolving U.S. Asset Based Loan from \$150 million to \$200 million, decreased the interest rate 25 basis points and made other minor amendments to the loan agreement. The Company's borrowing under its U.S. Asset Based Loan remains at \$80 million.

About TTM

TTM Technologies, Inc. is a major global printed circuit board manufacturer, focusing on quick-turn and technologically advanced PCBs, backplane assemblies and electro-mechanical solutions. TTM stands for time-to-market, representing how TTM's time-critical, one-stop manufacturing services enable customers to shorten the time required to develop new products and bring them to market. Additional information can be found at www.ttm.com.

Forward-Looking Statements

This release contains forward-looking statements that relate to future events or performance. TTM cautions you that such statements are simply predictions and actual events or results may differ materially. These statements reflect TTM's current expectations, and TTM does not undertake to update or revise these forward looking statements, even if experience or future changes make it clear that any projected results expressed or implied in this or other TTM statements will not be realized. Further, these statements involve risks and uncertainties, many of which are beyond TTM's control, which could cause actual results to differ materially from the forward-looking statements. These risks and uncertainties include, but are not limited to, the successful integration of Viasystems, general market and economic conditions, including interest rates, currency exchange rates and consumer spending, demand for TTM's products, market pressures on prices of TTM's products, warranty claims, changes in product mix, contemplated significant capital expenditures and related financing requirements, TTM's dependence upon a small number of customers and other factors set forth in the "Risk Factors" and "Management's Discussion and Analysis of Financial Condition and Results of Operations" sections of the Company's public reports filed with the SEC.

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